

N-Channel 25 V (D-S) MOSFET



| PRODUCT SUMMARY | | | | | |
|--|---------|--|--|--|--|
| V _{DS} (V) | 25 | | | | |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$ | 0.00265 | | | | |
| $R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$ | 0.00390 | | | | |
| Q _g typ. (nC) | 13.2 | | | | |
| I _D (A) | 60 a, g | | | | |
| Configuration | Single | | | | |

FEATURES

• TrenchFET® Gen IV power MOSFET



 \bullet Optimized $Q_g,\ Q_{gd},\ and\ Q_{gd}/Q_{gs}$ ratio reduces switching related power loss

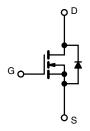
COMPLIANT HALOGEN **FREE**

100 % R_a and UIS tested

· Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- · Synchronous rectification
- High power density DC/DC
- Synchronous buck converter
- · Load switching



N-Channel MOSFET

| ORDERING INFORMATION | |
|---------------------------------|----------------------|
| Package | PowerPAK SO-8 Single |
| Lead (Pb)-free and halogen-free | SiRA26DP-T1-RE3 |

| PARAMETER | | SYMBOL | LIMIT | UNIT | |
|--|--|-----------------------------------|---------------------|------|--|
| Drain-source voltage | | V _{DS} | 25 | V | |
| Gate-source voltage | | V _{GS} | +16 / -12 | | |
| Continuous drain current (T _J = 150 °C) | T _C = 25 °C | | 60 ^a | | |
| | T _C = 70 °C | 1 , | 60 ^a | | |
| | T _A = 25 °C | I _D | 30.3 b, c | | |
| | T _A = 70 °C | | 24.2 b, c | | |
| Pulsed drain current (t = 100 μs) | | I _{DM} | 150 | Α | |
| Continuous accuracy during displacement | T _C = 25 °C | | 39.1 | | |
| Continuous source-drain diode current | T _A = 25 °C | I _S | 3.5 ^{b, c} | | |
| Single pulse avalanche current | 1 0.1 ml l | I _{AS} | 25 | | |
| Single pulse avalanche energy L = 0.1 mH | | E _{AS} | 31.2 | mJ | |
| | T _C = 25 °C | | 43.1 | | |
| Manifestore and address of the state of | T _C = 70 °C | | 27.5 | 14/ | |
| Maximum power dissipation | T _A = 25 °C | P _D | 3.9 b, c | W | |
| | T _A = 70 °C | | 2.5 ^{b, c} | | |
| Operating junction and storage temperature range | | T _J , T _{stg} | -55 to +150 | 20 | |
| Soldering recommendations (peak tempera | Soldering recommendations (peak temperature) c | | 260 | °C | |

| THERMAL RESISTANCE RATING | as . | | | | |
|--|--------------|-------------------|---------|---------|------|
| PARAMETER | | SYMBOL | TYPICAL | MAXIMUM | UNIT |
| Maximum junction-to-ambient ^b | t ≤ 10 s | R_{thJA} | 24 | 32 | °C/W |
| Maximum junction-to-case (drain) | Steady state | R _{thJC} | 2.3 | 2.9 | C/VV |

Notes

- Package limited
 Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

 Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

 Maximum under steady state conditions is 70 °C/W

- $T_C = 25 \, ^{\circ}C$



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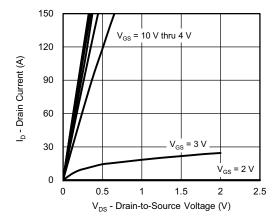
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNIT | |
|---|-------------------------|--|------|---------|---------|-------|--|
| Static | | | | | | | |
| Drain-source breakdown voltage | V_{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 25 | - | - | V | |
| V _{DS} temperature coefficient | $\Delta V_{DS}/T_{J}$ | I _D = 10 mA | - | 19 | - | 1400 | |
| V _{GS(th)} temperature coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | - | -4.5 | - | mV/°C | |
| Gate-source threshold voltage | V _{GS(th)} | $V_{DS} = V_{GS}, I_D = 250 \mu A$ | 1 | - | 2.5 | V | |
| Gate-source leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = +16 / -12 \text{ V}$ | - | - | 100 | nA | |
| 7 | | $V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$ | ı | - | 1 | μΑ | |
| Zero gate voltage drain current | I _{DSS} | V _{DS} =25 V, V _{GS} = 0 V, T _J = 70 °C | ı | - | 15 | | |
| On-state drain current ^a | I _{D(on)} | $V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$ | 40 | - | - | Α | |
| D | D | V _{GS} = 10 V, I _D = 15 A | - | 0.00215 | 0.00265 | - | |
| Drain-source on-state resistance ^a | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$ | ı | 0.00315 | 0.00390 | Ω | |
| Forward transconductance a | 9 _{fs} | V _{DS} = 15 V, I _D = 15 A | - | 88 | - | S | |
| Dynamic ^b | | | | | | l | |
| Input capacitance | C _{iss} | | - | 2247 | - | | |
| Output capacitance | C _{oss} | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | - | 730 | - | pF | |
| Reverse transfer capacitance | C _{rss} | | - | 105 | - | ┦ . | |
| Fatal anto about | 0 | V _{DS} = 10 V, V _{GS} = 10 V, I _D =10 A | ı | 29 | 44 | | |
| Total gate charge | Q_g | | - | 13.2 | 20 | | |
| Gate-source charge | Q _{gs} | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$ | ı | 5.4 | - | nC | |
| Gate-drain charge | Q_{gd} | | _ | 2.2 | - | | |
| Gate resistance | R_{g} | f = 1 MHz | 0.2 | 0.8 | 1.5 | Ω | |
| Turn-on delay time | t _{d(on)} | | - | 9 | 18 | | |
| Rise time | t _r | $V_{DD} = 10 \text{ V}, R_L = 1 \Omega, I_D \cong 10 \text{ A},$ | _ | 23 | 46 | | |
| Turn-off delay time | t _{d(off)} | $V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$ | 1 | 16 | 36 | 1 | |
| Fall time | t _f | | _ | 8 | 16 | | |
| Turn-on delay time | t _{d(on)} | | - | 17 | 34 | ns | |
| Rise time | t _r | $V_{DD} = 10 \text{ V}, R_L = 1 \Omega, I_D \cong 10 \text{ A},$ | 1 | 48 | 96 | | |
| Turn-off delay time | t _{d(off)} | V_{GEN} = 4.5 V, R_g = 1 Ω | _ | 13 | 26 | | |
| Fall time | t _f | | _ | 13 | 26 | | |
| Drain-Source Body Diode Characteristi | cs | | | | | | |
| Continuous source-drain diode current | I _S | T _C = 25 °C | - | - | 35.4 | _ | |
| Pulse diode forward current | I _{SM} | | 1 | - | 150 | Α | |
| Body diode voltage | V_{SD} | $I_{S} = 5 \text{ A}, V_{GS} = 0 \text{ V}$ | - | 0.75 | 1.1 | V | |
| Body diode reverse recovery time | t _{rr} | | - | 29 | 58 | ns | |
| Body diode reverse recovery charge | Q _{rr} | 1 10 A 11/44 100 A/ - T 05 00 | - | 16 | 32 | nC | |
| Reverse recovery fall time | t _a | $I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | - | 12 | - | | |
| Reverse recovery rise time | t _b | | _ | 17 | - | ns | |

Notes

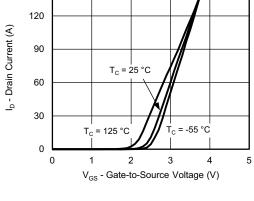
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



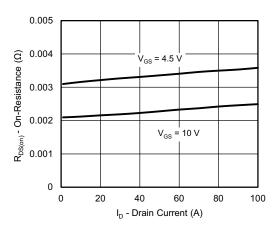


Output Characteristics

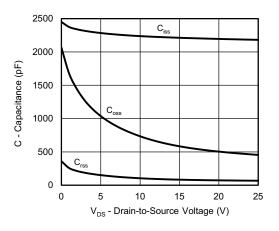


150

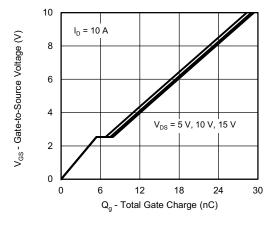
Transfer Characteristics



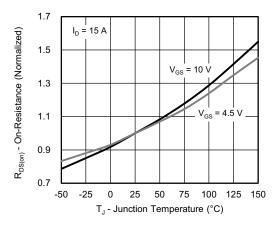
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

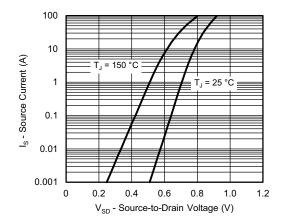


Gate Charge

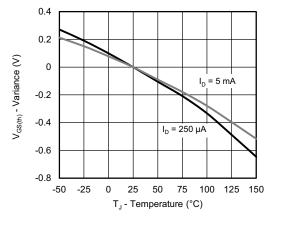


On-Resistance vs. Junction Temperature

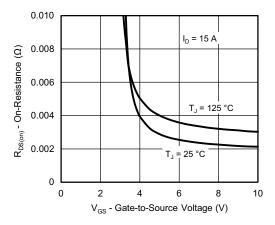




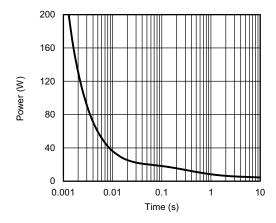
Source-Drain Diode Forward Voltage



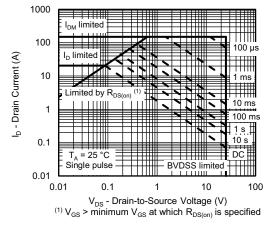
Threshold Voltage



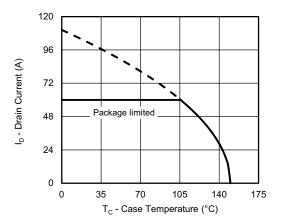
On-Resistance vs. Gate-to-Source Voltage



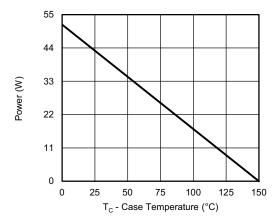
Single Pulse Power, Junction-to-Ambient



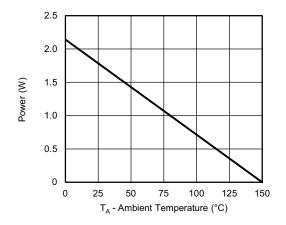
Safe Operating Area, Junction-to-Ambient



Current Derating a





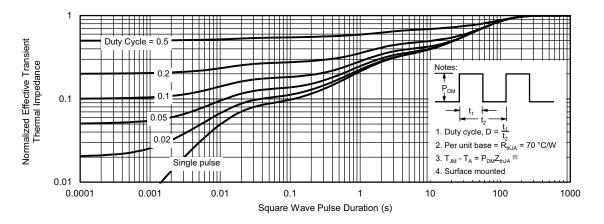


Power, Junction-to-Ambient

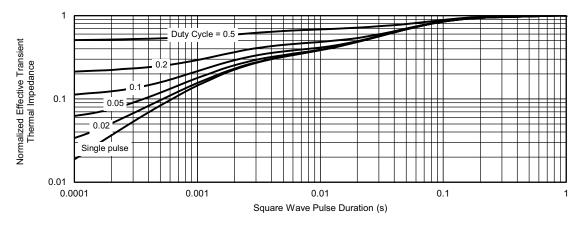
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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DWG: 5881

PowerPAK® SO-8, (Single/Dual)

Notes 1. Inch will govern. 2 Dimensions exclusive of mold gate burrs.

3. Dimensions exclusive of mold flash and cutting burrs.

Backside View of Dual Pad

| DIM. | | MILLIMETERS | | | INCHES | | |
|------|------|-------------|------|-------------|------------|-------|--|
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX | |
| Α | 0.97 | 1.04 | 1.12 | 0.038 | 0.041 | 0.044 | |
| A1 | | - | 0.05 | 0 | _ | 0.002 | |
| b | 0.33 | 0.41 | 0.51 | 0.013 | 0.016 | 0.020 | |
| С | 0.23 | 0.28 | 0.33 | 0.009 | 0.011 | 0.013 | |
| D | 5.05 | 5.15 | 5.26 | 0.199 | 0.203 | 0.207 | |
| D1 | 4.80 | 4.90 | 5.00 | 0.189 | 0.193 | 0.197 | |
| D2 | 3.56 | 3.76 | 3.91 | 0.140 | 0.148 | 0.154 | |
| D3 | 1.32 | 1.50 | 1.68 | 0.052 | 0.059 | 0.066 | |
| D4 | | 0.57 typ. | | 0.0225 typ. | | | |
| D5 | | 3.98 typ. | | | 0.157 typ. | | |
| Е | 6.05 | 6.15 | 6.25 | 0.238 | 0.242 | 0.246 | |
| E1 | 5.79 | 5.89 | 5.99 | 0.228 | 0.232 | 0.236 | |
| E2 | 3.48 | 3.66 | 3.84 | 0.137 | 0.144 | 0.151 | |
| E3 | 3.68 | 3.78 | 3.91 | 0.145 | 0.149 | 0.154 | |
| E4 | | 0.75 typ. | | | 0.030 typ. | | |
| е | | 1.27 BSC | | | 0.050 BSC | | |
| K | | 1.27 typ. | | | 0.050 typ. | | |
| K1 | 0.56 | - | - | 0.022 | - | - | |
| Н | 0.51 | 0.61 | 0.71 | 0.020 | 0.024 | 0.028 | |
| L | 0.51 | 0.61 | 0.71 | 0.020 | 0.024 | 0.028 | |
| L1 | 0.06 | 0.13 | 0.20 | 0.002 | 0.005 | 0.008 | |
| θ | 0° | - | 12° | 0° | - | 12° | |
| W | 0.15 | 0.25 | 0.36 | 0.006 | 0.010 | 0.014 | |
| М | | 0.125 typ. | | | 0.005 typ. | | |

Revison: 13-Feb-17 1 Document Number: 71655



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



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